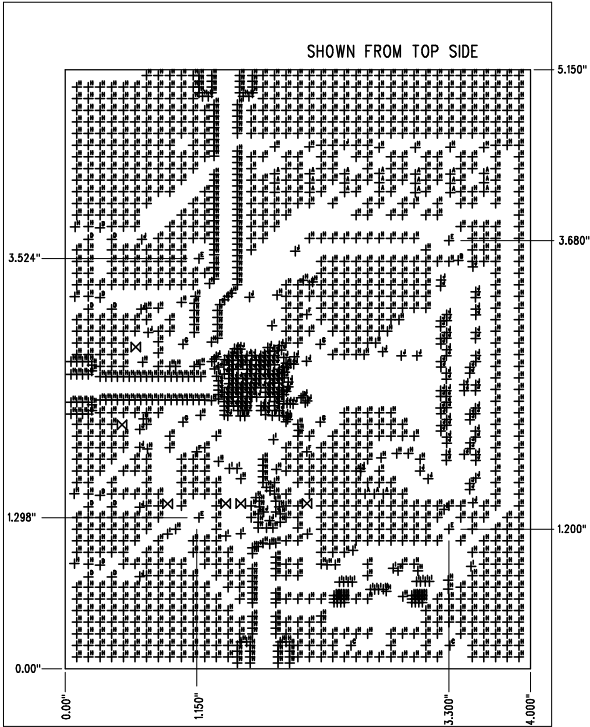
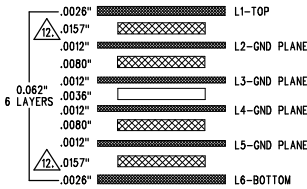


SIZE	QTY	SYM	PLATED	TOL
0.065	6	⊠	YES	+/-0.003
0.035	24	⊠ ^A	YES	+/-0.003
0.05	2	⊠ ^B	NO	+/-0.003
0.095	2	⊠ ^C	YES	+/-0.003
0.03228	12	⊠ ^D	YES	+/-0.003
0.14173	4	⊠ ^E	NO	+/-0.003
0.08	3	⊠ ^F	NO	+/-0.003
0.1252	4	⊠ ^G	NO	+/-0.003
0.01	1379	⊠ ^H	YES	+/-0.003
0.016	22	⊠ ^I	YES	+/-0.003
0.006	256	⊠ ^J	YES	+/-0.003



REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	0	1ST PROTOTYPE	D. STUETZLE 11-17-11

LAYER STRUCTURE



NOTES: UNLESS OTHERWISE SPECIFIED

- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-408HR OR EQUIVALENT.
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 6 LAYERS, FINISHED COPPER PLATING SHALL BE AS SPECIFIED IN FIG.2, "LAYER STRUCTURE", BELOW.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
-MACHINE THE EDGE CONNECTOR AS PER FIG.1 BELOW.
- DRILLING: -DRILL HOLES PER SCHEDULE, PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
- FINISH: -SWOBC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMERSION BOTH SIDES.
-SILKSCREEN LEGENDS SHALL BE WHITE NON-CONDUCTIVE EPOXY INK.
-SELECT HARD GOLD OVER NICKEL PLATE FOR THE .196 20 MIL DIAMETER PADS ASSOCIATED WITH U2.
-USE CONDUCTIVE FILL FOR THE X24 VIAS UNDERNEATH U3, U4
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
- BOARDS SHALL BE RoHS COMPLIANT.
- BOARDS SHALL BE PANELIZED USING ROUTE AND RETAIN METHOD.

UNLESS OTHERWISE SPECIFIED		APPROVALS		 1650 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-9900 WWW.LINEAR.COM LTC CONFIDENTIAL FOR CUSTOMER USE ONLY	
DIMENSIONS ARE IN INCHES TOLERANCES: 0.1XX" = ±0.01" 0.1XX" = ±0.005" INTERPRET DIM AND TOL PER ASME Y14.5M-1994 THIRD ANGLE PROJECTION		PCB DES.	D.STUETZLE		
		APP. ENG.	D.STUETZLE	TITLE: FABRICATION DRAWING	
				DPD RECEIVER MODULE	
				SIZE	IC NO.
				N/A	LTM9013
				FILENAME:	DC193IB.PCB
				SCALE = NONE	REV B
					SHT 1 OF 1